

## FEATURES

- ESD Protection for RS-232 Bus Pins
  - $\pm 15$ -kV Human-Body Model (HBM)
  - $\pm 8$ -kV IEC 61000-4-2, Contact Discharge
  - $\pm 15$ -kV IEC 61000-4-2, Air-Gap Discharge
- Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operate With 3-V to 5.5-V  $V_{CC}$  Supply
- Operate up to 1000 kbit/s
- Two Drivers and Two Receivers
- Low Standby Current . . . 1  $\mu$ A Typ
- External Capacitors . . .  $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply

## APPLICATIONS

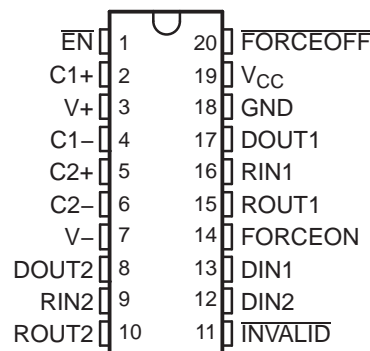
- Battery-Powered Systems
- PDAs
- Notebooks
- Laptops
- Palmtop PCs
- Hand-Held Equipment

## DESCRIPTION/ORDERING INFORMATION

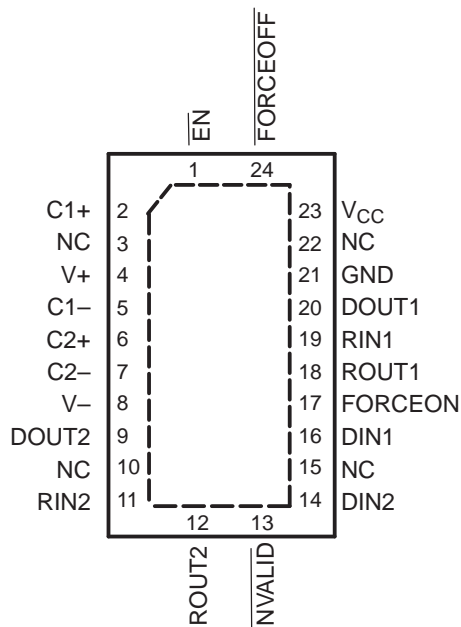
The SN65C3223E and SN75C3223E consist of two line drivers, two line receivers, and a dual charge-pump circuit with  $\pm 15$ -kV ESD protection pin to pin (serial-port connection pins, including GND). These devices meet the requirements of TIA/EIA-232-F and provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The devices operate at typical data signaling rates up to 1000 kbit/s.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when  $\overline{\text{FORCEON}}$  is low and  $\overline{\text{FORCEOFF}}$  is high. During this mode of operation, if the devices do not sense a valid RS-232 signal, the driver outputs are disabled. If  $\overline{\text{FORCEOFF}}$  is set low and EN is high, both drivers and receivers are shut off, and the supply current is reduced to 1 mA. Disconnecting the serial port or turning off the peripheral drivers causes auto-powerdown to occur. Auto-powerdown can be disabled when  $\overline{\text{FORCEON}}$  and  $\overline{\text{FORCEOFF}}$  are high. With auto-powerdown enabled, the devices are activated automatically when a valid signal is applied to any receiver input. The  $\overline{\text{INVALID}}$  output is used to notify the user if an RS-232 signal is present at any receiver input.  $\overline{\text{INVALID}}$  is high (valid data) if any receiver input voltage is greater than 2.7 V or less than  $-2.7$  V, or has been between  $-0.3$  V and 0.3 V for less than 30  $\mu$ s.  $\overline{\text{INVALID}}$  is low (invalid data) if the receiver input voltage is between  $-0.3$  V and 0.3 V for more than 30  $\mu$ s. Refer to Figure 4 for receiver input levels.

DB, DW, OR PW PACKAGE  
(TOP VIEW)



RHL PACKAGE  
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**SN65C3223E, SN75C3223E**  
**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVERS/RECEIVERS**  
**WITH  $\pm 15$ -kV ESD PROTECTION**

SLLS727A–MAY 2006–REVISED JULY 2006

**ORDERING INFORMATION**

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC – DW	Tube of 25	SN75C3223EDW	75C3223E
		Reel of 2000	SN75C3223EDWR	
	SSOP – DB	Tube of 70	SN75C3223EDB	MY223E
		Reel of 2000	SN75C3223EDBR	
	TSSOP – PW	Tube of 70	SN75C3223EPW	MY223E
		Reel of 2000	SN75C3223EPWR	
–40°C to 85°C	SOIC – DW	Tube of 25	SN65C3223EDW	65C3223E
		Reel of 2000	SN65C3223EDWR	
	SSOP – DB	Tube of 70	SN65C3223EDB	MU223E
		Reel of 2000	SN65C3223EDBR	
	TSSOP – PW	Tube of 70	SN65C3223EPW	MU223E
		Reel of 2000	SN65C3223EPWR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

**FUNCTION TABLES**

**Each Driver<sup>(1)</sup>**

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown disabled
H	H	H	X	L	
L	L	H	Yes	H	Normal operation with auto-powerdown enabled
H	L	H	Yes	L	
L	L	H	No	Z	Powered off by auto-powerdown feature
H	L	H	No	Z	

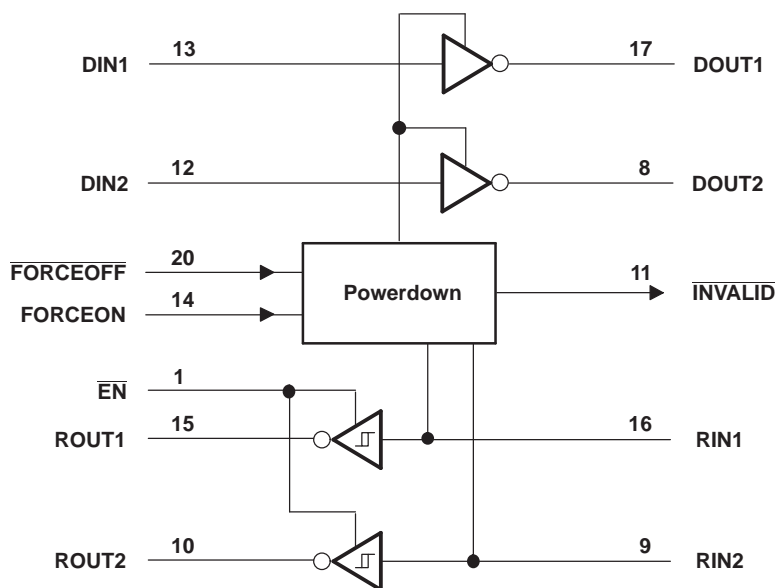
(1) H = high level, L = low level, X = irrelevant, Z = high impedance

**Each Receiver<sup>(1)</sup>**

INPUTS			OUTPUT DOUT
RIN	EN	VALID RIN RS-232 LEVEL	
L	L	X	H
H	L	X	L
X	H	X	Z
Open	L	No	H

(1) H = high level, L = low level, X = irrelevant,  
Z = high impedance (off),  
Open = input disconnected or connected driver off

**LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers are for the DB, DW, and PW packages.

**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		−0.3	6	V
V+	Positive-output supply voltage range <sup>(2)</sup>		−0.3	7	V
V−	Negative-output supply voltage range <sup>(2)</sup>		0.3	−7	V
V+ − V−	Supply voltage difference <sup>(2)</sup>			13	V
V <sub>I</sub>	Input voltage range	Driver (FORCEOFF, FORCEON, EN)	−0.3	6	V
		Receiver	−25	25	
V <sub>O</sub>	Output voltage range	Driver	−13.2	13.2	V
		Receiver (INVALID)	−0.3	V <sub>CC</sub> + 0.3	
θ <sub>JA</sub>	Package thermal impedance <sup>(3)(4)</sup>	DB package		70	°C/W
		DW package		58	
		PW package		83	
		RHL package		TBD	
T <sub>J</sub>	Operating virtual junction temperature			150	°C
T <sub>std</sub>	Storage temperature range		−65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) Maximum power dissipation is a function of T<sub>J</sub>(max),  $\theta_{JA}$ , and T<sub>A</sub>. The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A) / \theta_{JA}$ . Operating at the absolute maximum T<sub>J</sub> of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

# SN65C3223E, SN75C3223E

## 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVERS/RECEIVERS

### WITH $\pm 15$ -kV ESD PROTECTION

SLLS727A—MAY 2006—REVISED JULY 2006

#### Recommended Operating Conditions<sup>(1)</sup>

See Figure 6

				MIN	NOM	MAX	UNIT
Supply voltage			V <sub>CC</sub> = 3.3 V	3	3.3	3.6	V
			V <sub>CC</sub> = 5 V	4.5	5	5.5	
V <sub>IH</sub>	Driver and control high-level input voltage	DIN, <del>EN</del> , FORCEOFF, FORCEON	V <sub>CC</sub> = 3.3 V	2			V
			V <sub>CC</sub> = 5 V	2.4			
V <sub>IL</sub>	Driver and control low-level input voltage	DIN, <del>EN</del> , FORCEOFF, FORCEON		0.8			V
V <sub>I</sub>	Driver and control input voltage	DIN, <del>EN</del> , FORCEOFF, FORCEON		0	5.5		V
	Receiver input voltage			−25	25		
T <sub>A</sub>	Operating free-air temperature	SN75C3223E		0	70		°C
		SN65C3223E		−40	85		

(1) Test conditions are C1–C4 = 0.1  $\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ; C1 = 0.047  $\mu\text{F}$ , C2–C4 = 0.33  $\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

#### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER			TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
I <sub>I</sub>	Input leakage current	EN, FORCEOFF, FORCEON		±0.01	±1		μA
I <sub>CC</sub>	Supply current	Auto-powerdown disabled	V <sub>CC</sub> = 3.3 V or 5 V, T <sub>A</sub> = 25°C, No load, FORCEOFF and FORCEON at V <sub>CC</sub>	0.3	1		mA
		Powered off	No load, FORCEOFF at GND	1	10		μA
		Auto-powerdown enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded	1	10		

(1) Test conditions are C1–C4 = 0.1  $\mu\text{F}$  at  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ ; C1 = 0.047  $\mu\text{F}$ , C2–C4 = 0.33  $\mu\text{F}$  at  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ .

(2) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

## DRIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub> High-level output voltage	DOUT at R <sub>L</sub> = 3 k $\Omega$ to GND	5	5.4		V
V <sub>OL</sub> Low-level output voltage	DOUT at R <sub>L</sub> = 3 k $\Omega$ to GND	–5	–5.4		V
I <sub>IH</sub> High-level input current	V <sub>I</sub> = V <sub>CC</sub>		$\pm 0.01$	$\pm 1$	$\mu$ A
I <sub>IL</sub> Low-level input current	V <sub>I</sub> at GND		$\pm 0.01$	$\pm 1$	$\mu$ A
I <sub>OS</sub> Short-circuit output current <sup>(3)</sup>	V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 0 V		$\pm 35$	$\pm 60$	mA
	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0 V				
r <sub>o</sub> Output resistance	V <sub>CC</sub> , V <sub>+</sub> , and V <sub>–</sub> = 0 V, V <sub>O</sub> = $\pm 2$ V	300	10M		$\Omega$
I <sub>OZ</sub> Output leakage current	FORCEOFF = GND, V <sub>CC</sub> = 3 V to 3.6 V, V <sub>O</sub> = $\pm 12$ V			$\pm 25$	$\mu$ A
	FORCEOFF = GND, V <sub>CC</sub> = 4.5 V to 5.5 V, V <sub>O</sub> = $\pm 12$ V			$\pm 25$	

(1) Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Maximum data rate (see Figure 1)	R <sub>L</sub> = 3 k $\Omega$ , One DOUT switching	C <sub>L</sub> = 1000 pF	250		kbit/s
		C <sub>L</sub> = 250 pF, V <sub>CC</sub> = 3 V to 4.5 V	1000		
		C <sub>L</sub> = 1000 pF, V <sub>CC</sub> = 4.5 V to 5.5 V	1000		
t <sub>sk(p)</sub> Pulse skew <sup>(3)</sup>	C <sub>L</sub> = 150 pF to 2500 pF, R <sub>L</sub> = 3 k $\Omega$ to 7 k $\Omega$ , See Figure 2		300		ns
SR(tr) Slew rate, transition region (see Figure 1)	R <sub>L</sub> = 7 k $\Omega$ , R <sub>L</sub> = 3 k $\Omega$	C <sub>L</sub> = 150 pF to 1000 pF	8	90	V/ $\mu$ s
		C <sub>L</sub> = 1000 pF	12	60	
		C <sub>L</sub> = 150 pF to 250 pF	24	150	

(1) Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Pulse skew is defined as |t<sub>PLH</sub> – t<sub>PHL</sub>| of each channel of the same device.

# SN65C3223E, SN75C3223E

## 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVERS/RECEIVERS

### WITH $\pm 15$ -kV ESD PROTECTION

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## RECEIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub> High-level output voltage	I <sub>OH</sub> = –1 mA	V <sub>CC</sub> – 0.6	V <sub>CC</sub> – 0.1		V
V <sub>OL</sub> Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V
V <sub>IT+</sub> Positive-going input threshold voltage	V <sub>CC</sub> = 3.3 V		1.6	2.4	V
	V <sub>CC</sub> = 5 V		1.9	2.4	
V <sub>IT–</sub> Negative-going input threshold voltage	V <sub>CC</sub> = 3.3 V	0.6	1.1		V
	V <sub>CC</sub> = 5 V	0.6	1.4		
V <sub>hys</sub> Input hysteresis (V <sub>IT+</sub> – V <sub>IT–</sub> )			0.5		V
I <sub>OZ</sub> Output leakage current	$\overline{\text{EN}} = V_{\text{CC}}$		$\pm 0.05$		$\mu\text{A}$
r <sub>i</sub> Input resistance	V <sub>I</sub> = $\pm 3$ V to $\pm 25$ V	3	5		k $\Omega$

(1) Test conditions are C1–C4 = 0.1  $\mu\text{F}$  at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu\text{F}$ , C2–C4 = 0.33  $\mu\text{F}$  at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP <sup>(2)</sup>	UNIT
t <sub>PLH</sub> Propagation delay time, low- to high-level output	C <sub>L</sub> = 150 pF, See Figure 3	150	ns
t <sub>PHL</sub> Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF, See Figure 3	150	ns
t <sub>en</sub> Output enable time	C <sub>L</sub> = 150 pF, R <sub>L</sub> = 3 k $\Omega$ , See Figure 4	200	ns
t <sub>dis</sub> Output disable time	C <sub>L</sub> = 150 pF, R <sub>L</sub> = 3 k $\Omega$ , See Figure 4	200	ns
t <sub>sk(p)</sub> Pulse skew <sup>(3)</sup>	See Figure 3	50	ns

(1) Test conditions are C1–C4 = 0.1  $\mu\text{F}$  at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; C1 = 0.047  $\mu\text{F}$ , C2–C4 = 0.33  $\mu\text{F}$  at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Pulse skew is defined as |t<sub>PLH</sub> – t<sub>PHL</sub>| of each channel of the same device.

## AUTO-POWERDOWN SECTION

### Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for <b>INVALID</b> high-level output voltage	FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$		2.7	V
$V_{T(valid)}$	Receiver input threshold for <b>INVALID</b> high-level output voltage	FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$	–2.7		V
$V_{T(invalid)}$	Receiver input threshold for <b>INVALID</b> low-level output voltage	FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$	–0.3	0.3	V
$V_{OH}$	<b>INVALID</b> high-level output voltage	$I_{OH} = 1 \text{ mA}$ , $\overline{\text{FORCEOFF}} = V_{CC}$ FORCEON = GND,	$V_{CC} - 0.6$		V
$V_{OL}$	<b>INVALID</b> low-level output voltage	$I_{OL} = 1.6 \text{ mA}$ , $\overline{\text{FORCEOFF}} = V_{CC}$ FORCEON = GND,		0.4	V

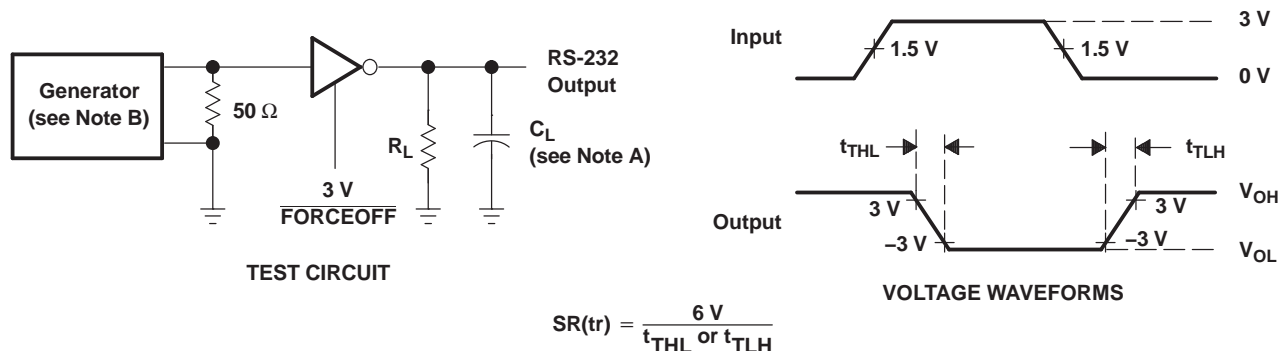
### Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TYP (1)	UNIT
$t_{valid}$	Propagation delay time, low- to high-level output	1	$\mu\text{s}$
$t_{invalid}$	Propagation delay time, high- to low-level output	30	$\mu\text{s}$
$t_{en}$	Supply enable time	100	$\mu\text{s}$

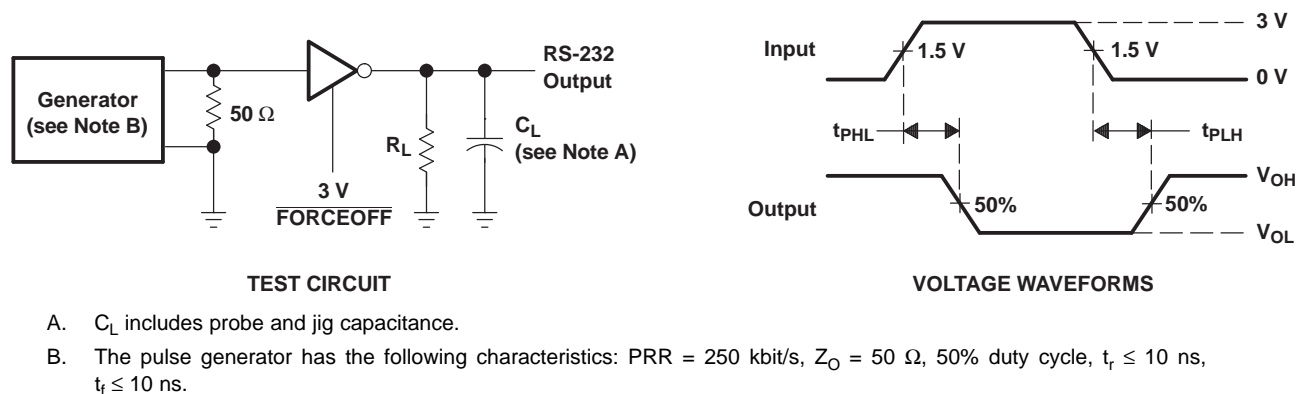
(1) All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^\circ\text{C}$ .

## PARAMETER MEASUREMENT INFORMATION



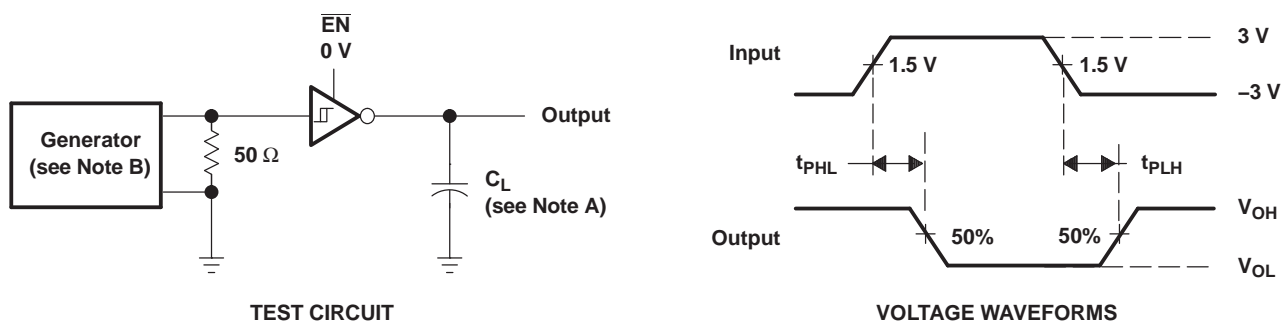
- A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\text{ ns}$ ,  $t_f \leq 10\text{ ns}$ .

Figure 1. Driver Slew Rate



- A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\text{ ns}$ ,  $t_f \leq 10\text{ ns}$ .

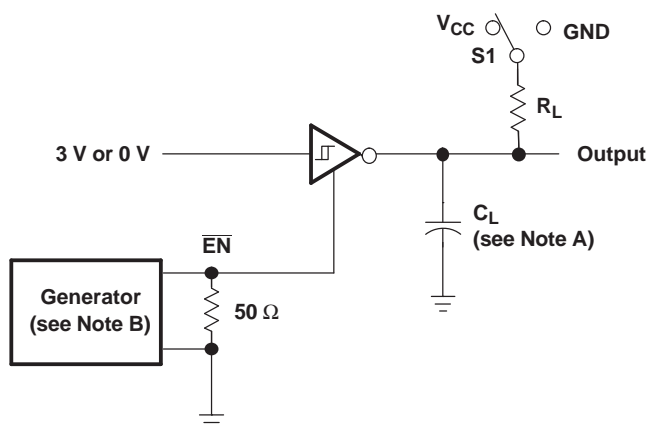
Figure 2. Driver Pulse Skew



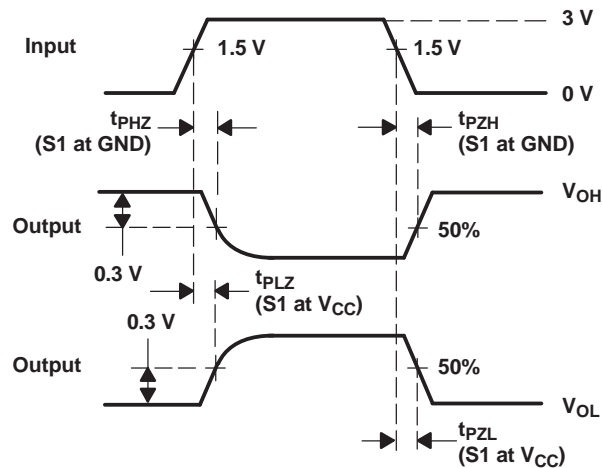
- A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics:  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\text{ ns}$ ,  $t_f \leq 10\text{ ns}$ .

Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT

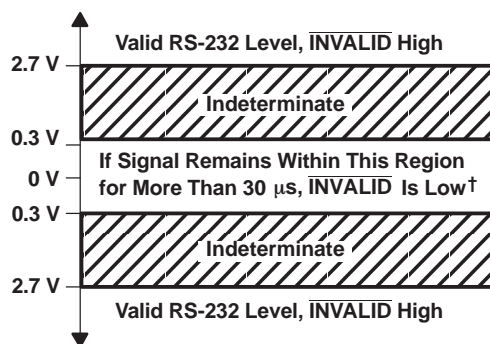
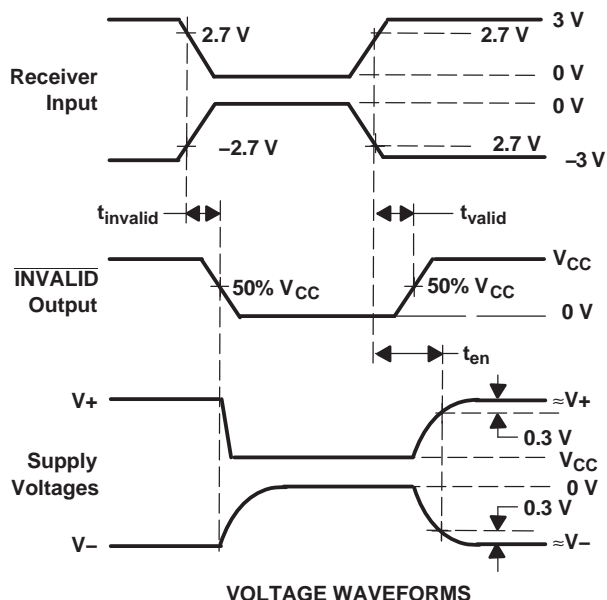
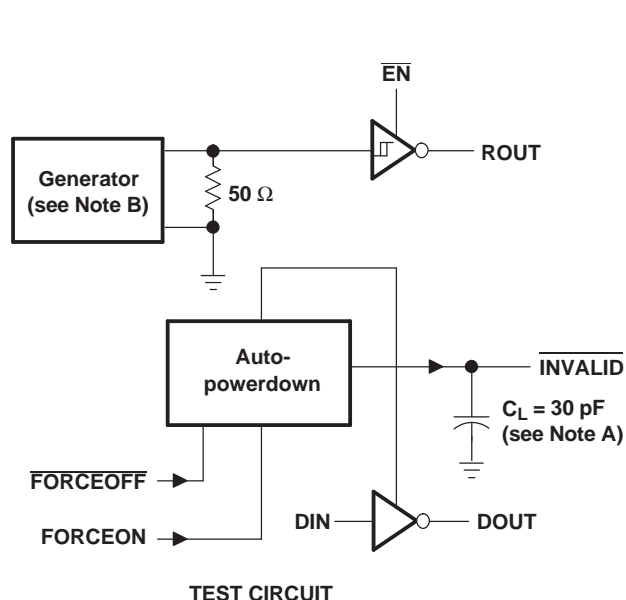


VOLTAGE WAVEFORMS

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $Z_O = 50\ \Omega$ , 50% duty cycle,  $t_r \leq 10\ \text{ns}$ ,  $t_f \leq 10\ \text{ns}$ .

Figure 4. Receiver Enable and Disable Times

## PARAMETER MEASUREMENT INFORMATION (continued)

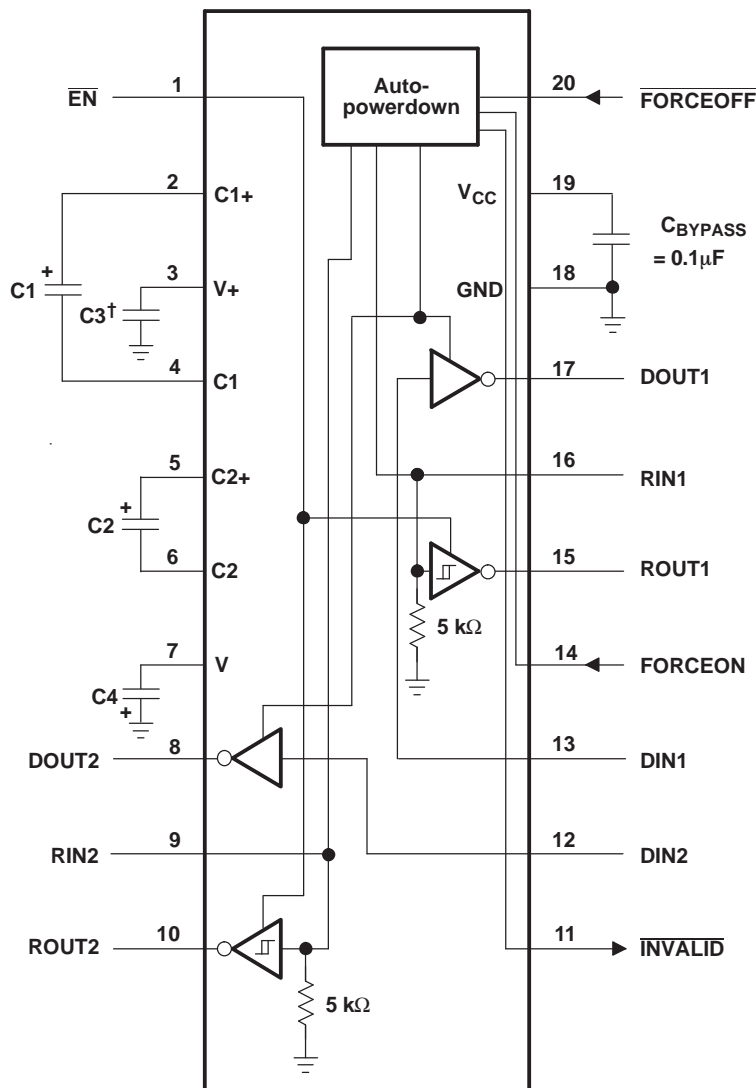


<sup>†</sup> Auto-powerdown disables drivers and reduces supply current to 1  $\mu$ A

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 5.  $\overline{\text{INVALID}}$  Propagation Delay Times and Supply Enabling Time

## APPLICATION INFORMATION



† C3 can be connected to  $V_{CC}$  or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

$V_{CC}$  vs CAPACITOR VALUES

$V_{CC}$	C1	C2, C3, and C4
3.3 V $\pm$ 0.3 V	0.1 $\mu$ F	0.1 $\mu$ F
5 V $\pm$ 0.5 V	0.047 $\mu$ F	0.33 $\mu$ F
3 V to 5.5 V	0.1 $\mu$ F	0.47 $\mu$ F

Figure 6. Typical Operating Circuit and Capacitor Values

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN65C3223EDBR</a>	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MU223E
SN65C3223EDBR.A	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MU223E
<a href="#">SN65C3223EDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C3223E
SN65C3223EDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C3223E
<a href="#">SN65C3223EDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C3223E
SN65C3223EDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65C3223E
<a href="#">SN65C3223EPW</a>	Obsolete	Production	TSSOP (PW)   20	-	-	Call TI	Call TI	-40 to 85	MU223E
<a href="#">SN75C3223EDB</a>	Active	Production	SSOP (DB)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MY223E
SN75C3223EDB.A	Active	Production	SSOP (DB)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MY223E
<a href="#">SN75C3223EDBR</a>	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MY223E
SN75C3223EDBR.A	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MY223E
<a href="#">SN75C3223EDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C3223E
SN75C3223EDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C3223E
<a href="#">SN75C3223EPW</a>	Obsolete	Production	TSSOP (PW)   20	-	-	Call TI	Call TI	0 to 70	MY223E
<a href="#">SN75C3223EPWR</a>	Obsolete	Production	TSSOP (PW)   20	-	-	Call TI	Call TI	0 to 70	MY223E

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

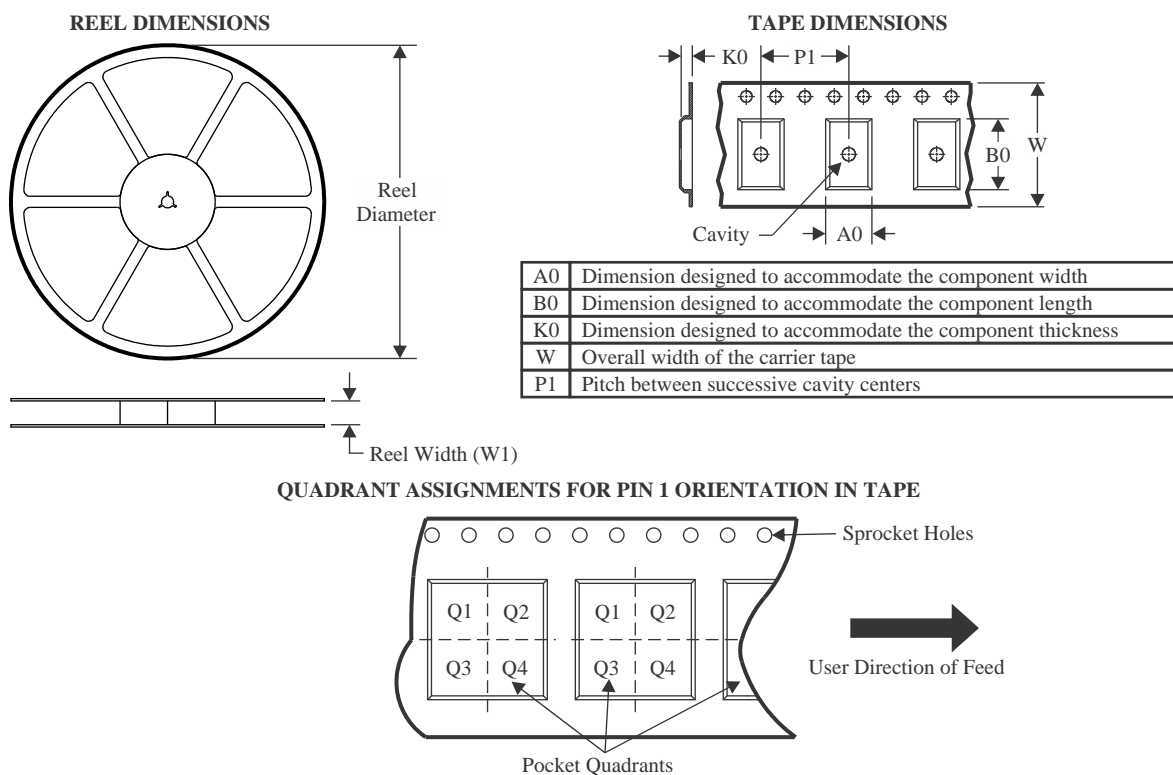
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

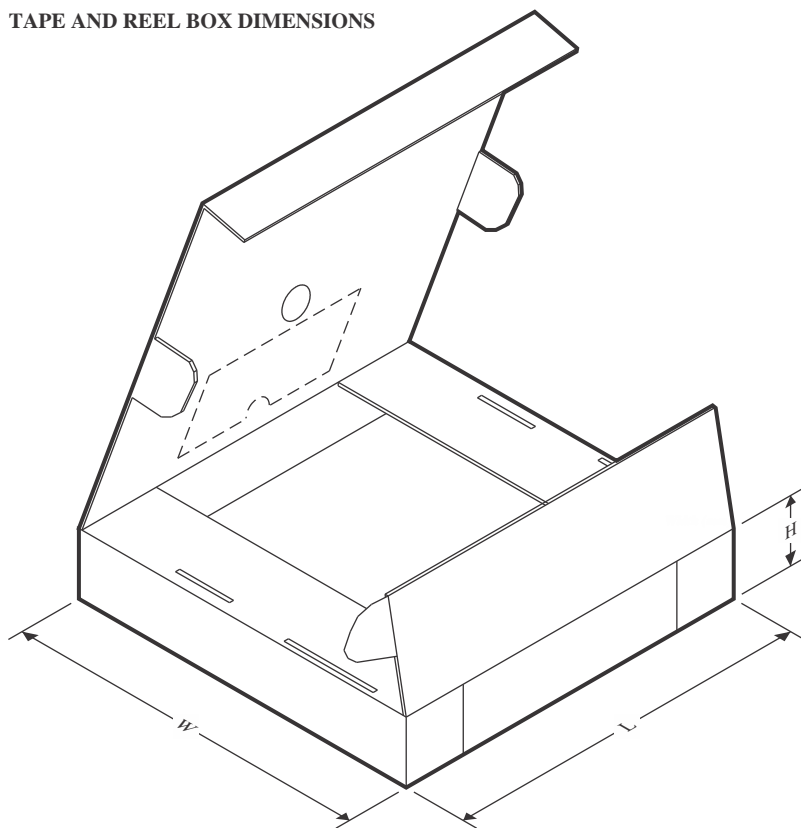
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65C3223EDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN65C3223EDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75C3223EDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN75C3223EDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

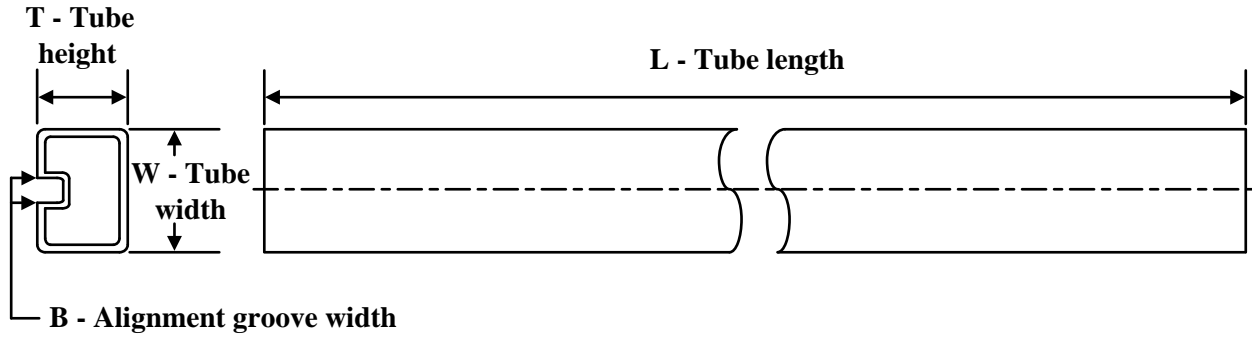
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

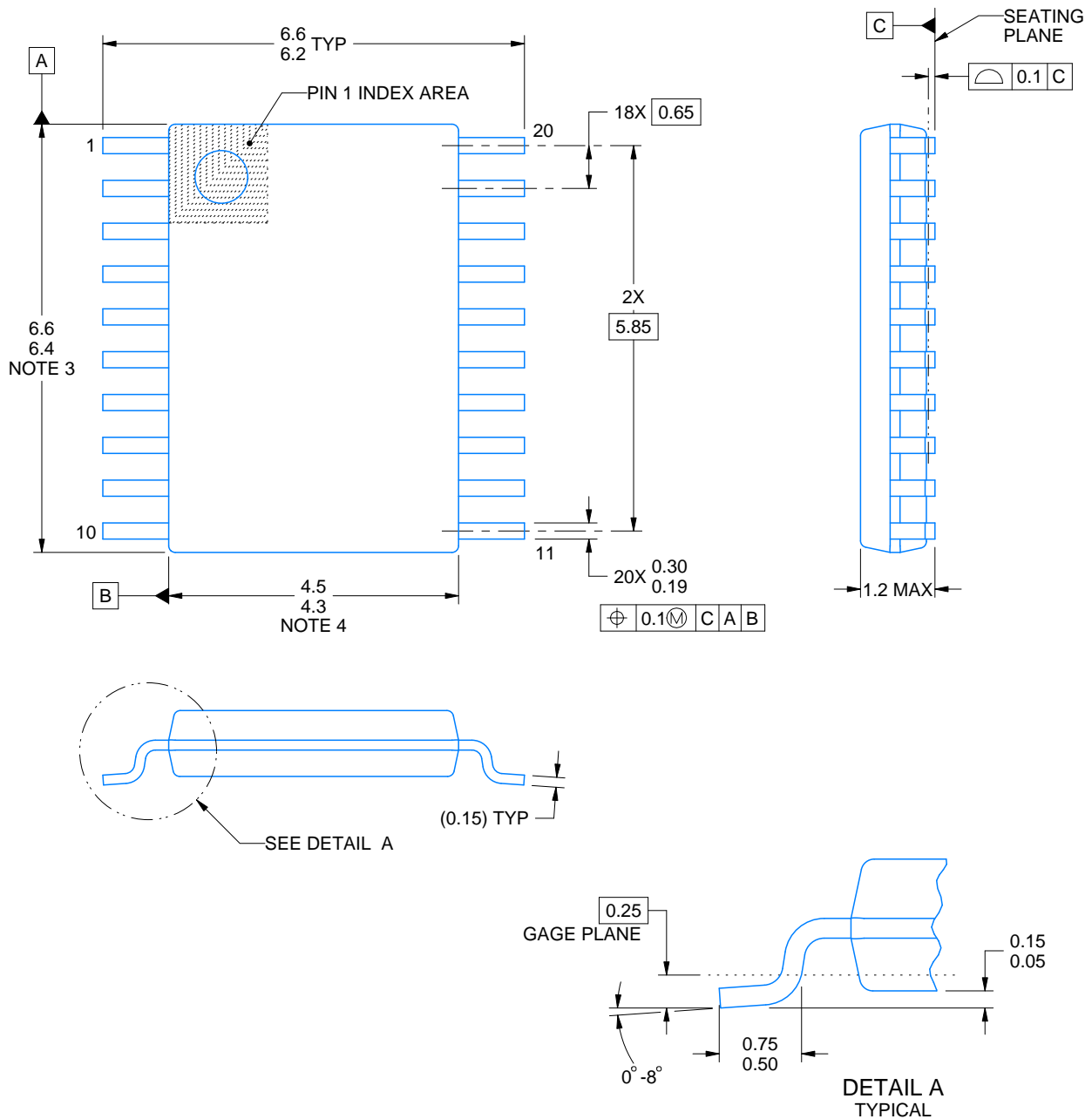
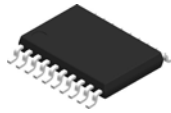
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65C3223EDBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN65C3223EDWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN75C3223EDBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN75C3223EDWR	SOIC	DW	20	2000	356.0	356.0	45.0

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN65C3223EDW	DW	SOIC	20	25	507	12.83	5080	6.6
SN65C3223EDW.A	DW	SOIC	20	25	507	12.83	5080	6.6
SN75C3223EDB	DB	SSOP	20	70	530	10.5	4000	4.1
SN75C3223EDB.A	DB	SSOP	20	70	530	10.5	4000	4.1



4220206/A 02/2017

## NOTES:

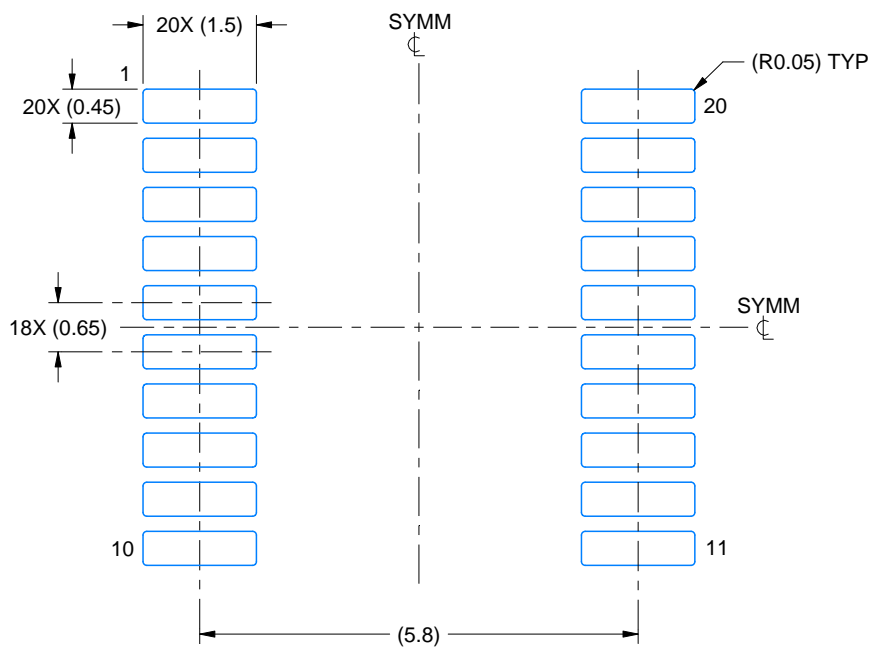
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

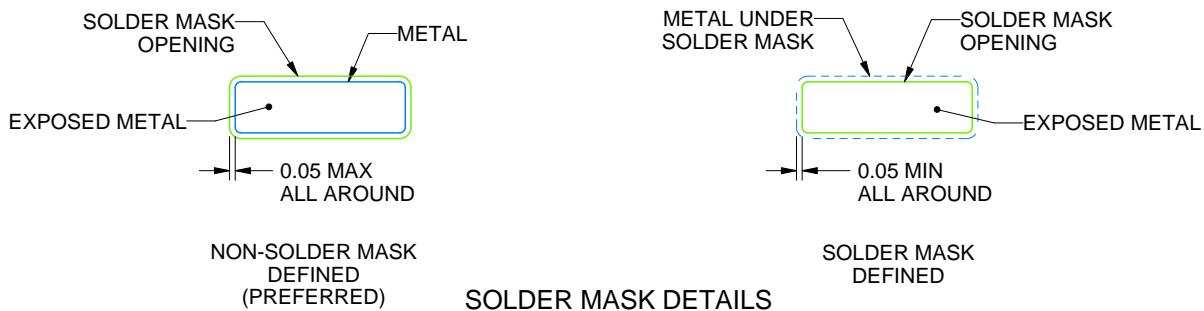
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

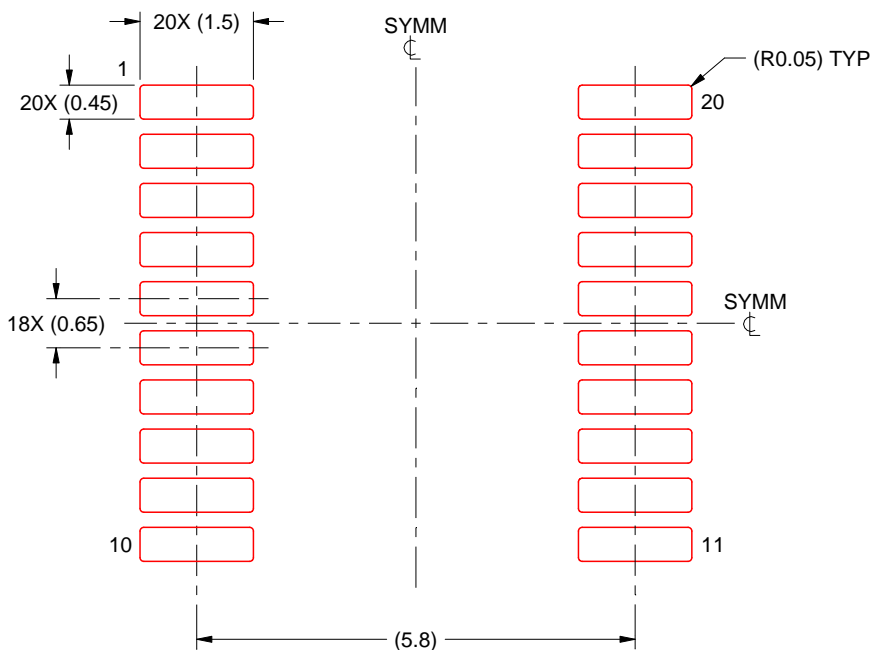
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

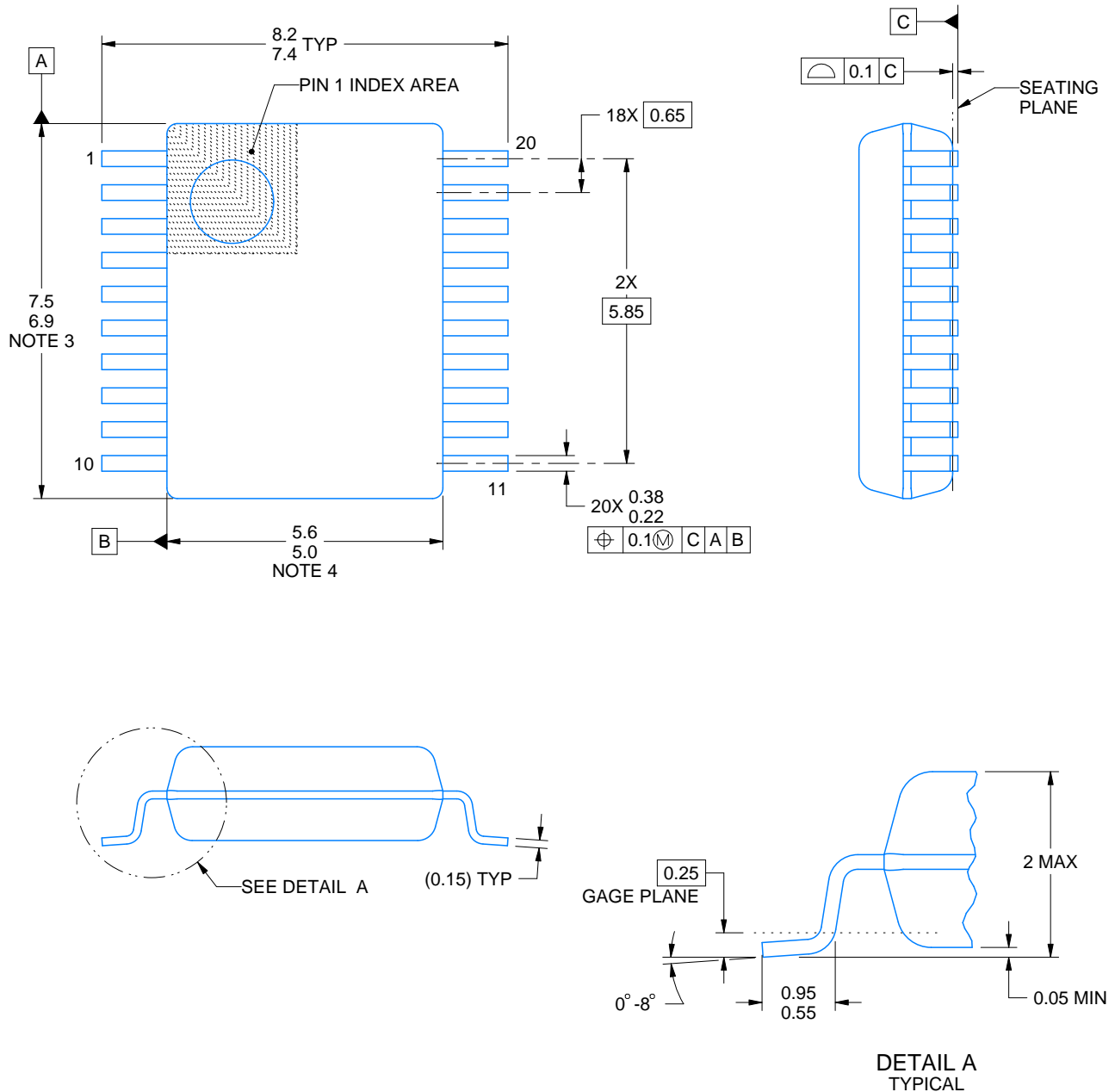
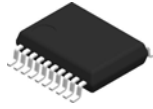


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4214851/B 08/2019

## NOTES:

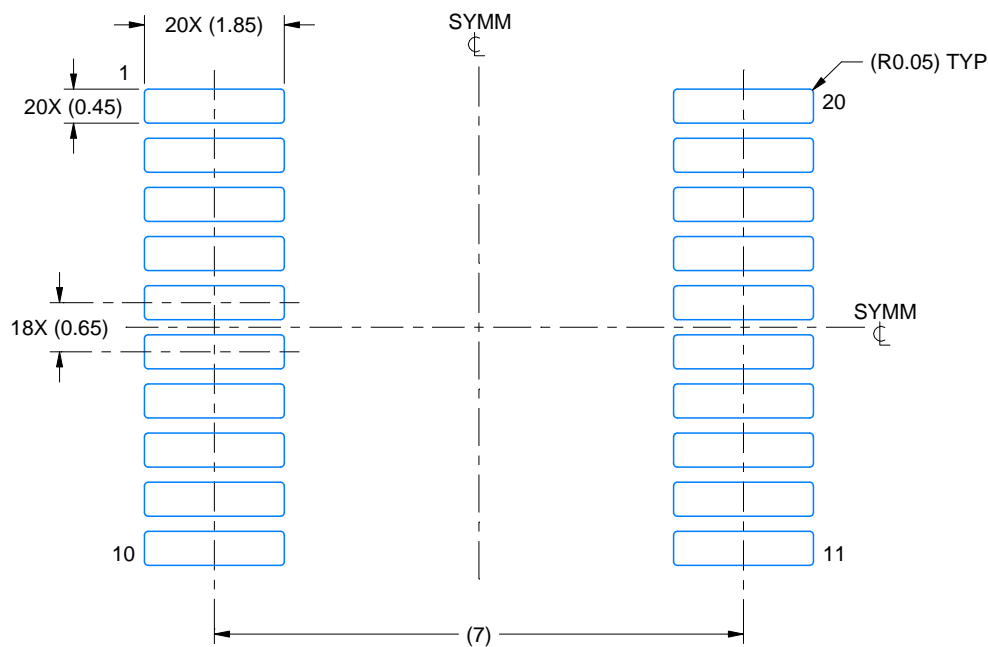
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

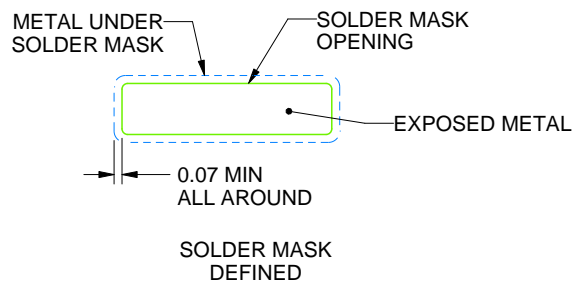
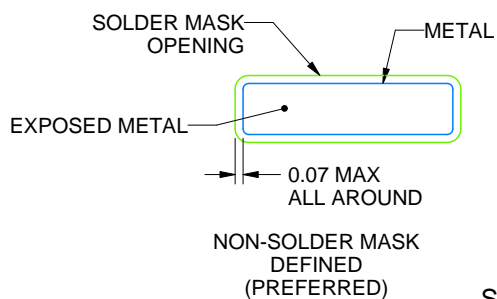
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

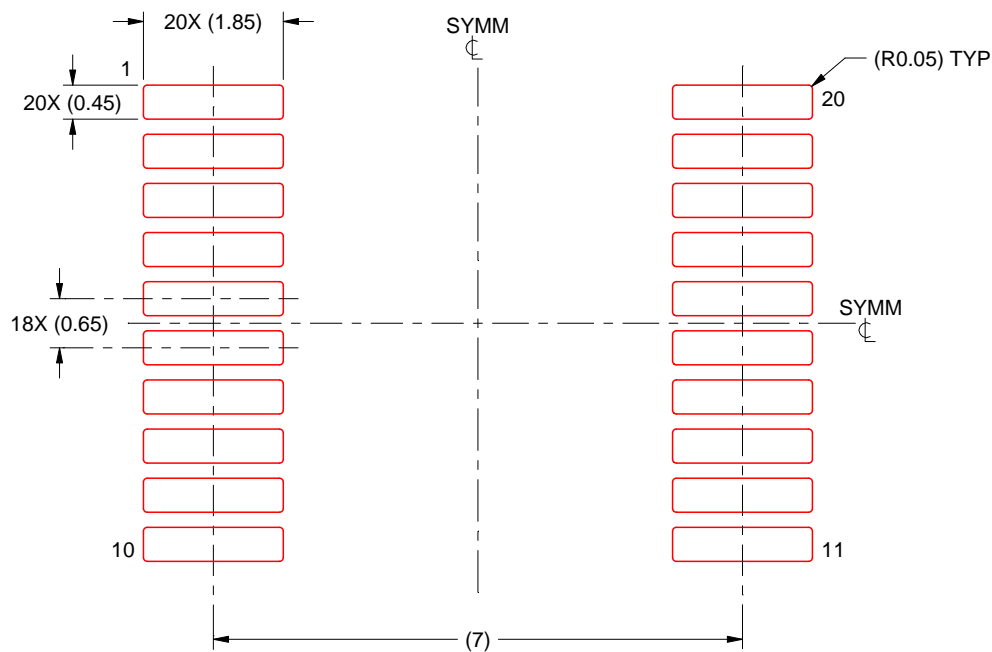
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

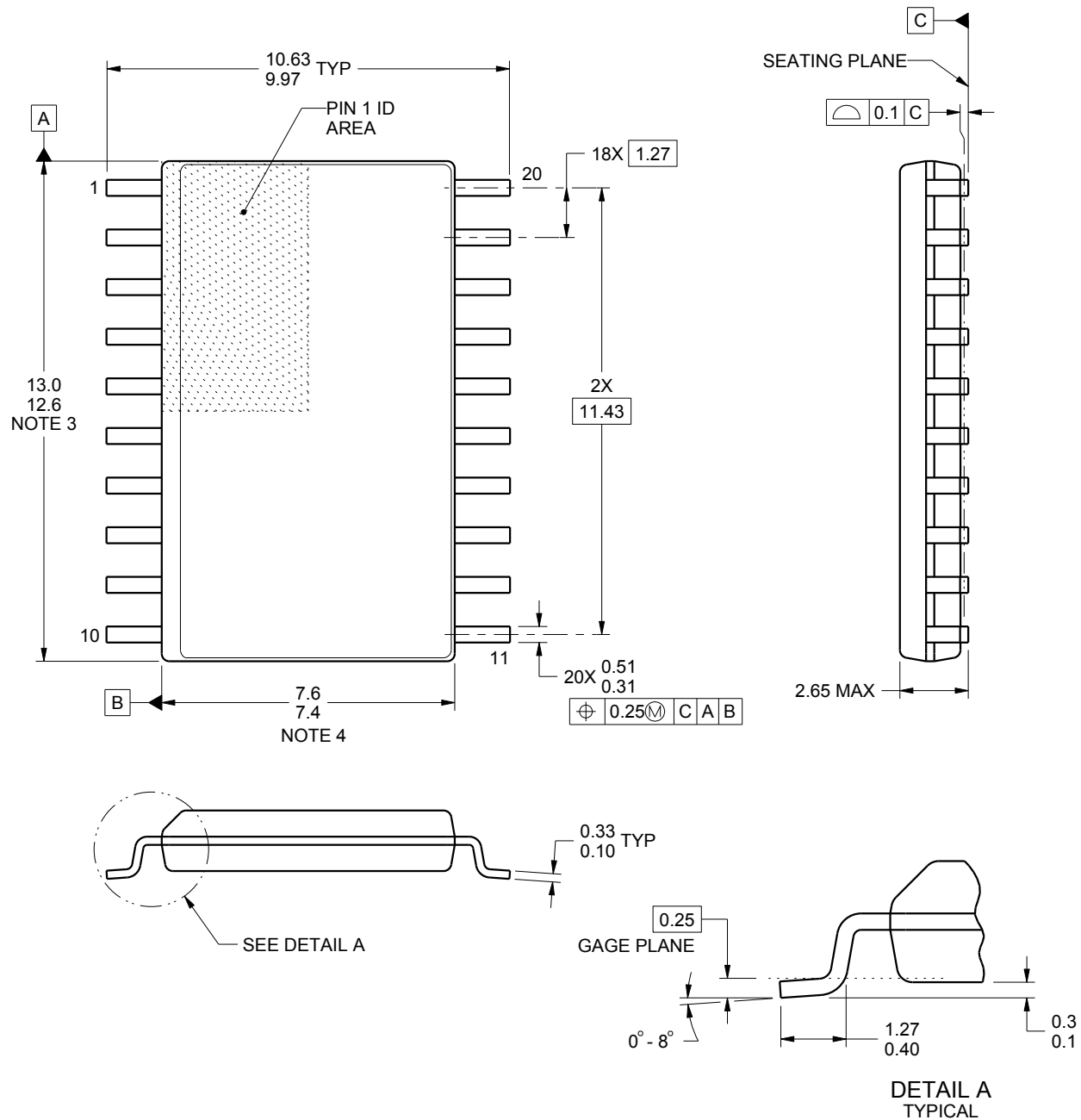
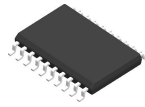


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4220724/A 05/2016

## NOTES:

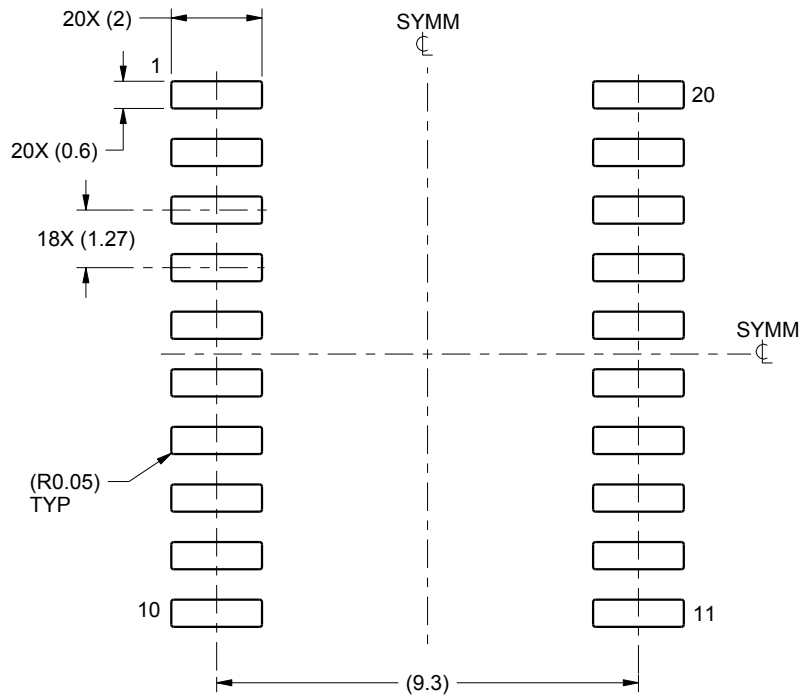
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

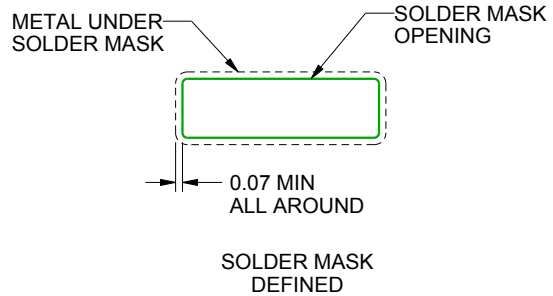
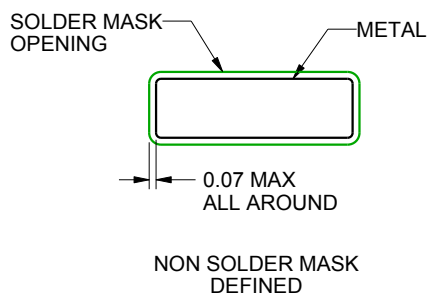
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

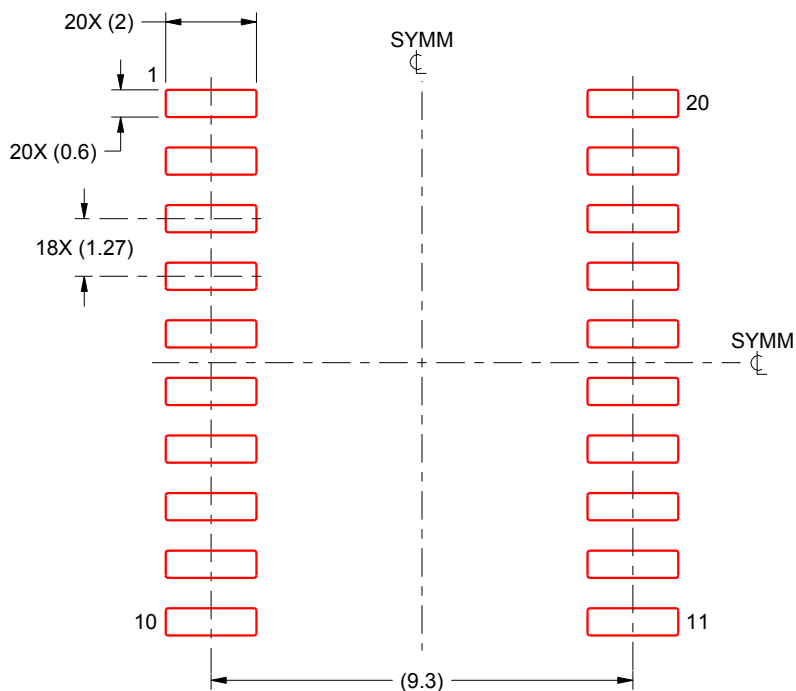
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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